SN54ABT162245, SN74ABT162245 16-BIT BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

SCBS239F - MARCH 1993 - REVISED JUNE 2004

- Members of the Texas Instruments Widebus™ Family
- A-Port Outputs Have Equivalent 25-Ω
 Series Resistors, So No External Resistors
 Are Required
- Typical V_{OLP} (Output Ground Bounce)
 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pins Minimize High-Speed Switching Noise
- I_{off} Supports Partial-Power-Down Mode Operation
- Flow-Through Architecture Optimizes PCB Layout
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

description/ordering information

The 'ABT162245 devices are 16-bit noninverting 3-state transceivers designed for synchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

These devices can be used as two 8-bit transceivers or one 16-bit transceiver. They allow data transmission from the A bus to the B bus or

from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses effectively are isolated.

The A-port outputs, which are designed to source or sink up to 12 mA, include equivalent 25- Ω series resistors to reduce overshoot and undershoot.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

SN74ABT162245 . . . DGG OR DL PACKAGE (TOP VIEW)

SN54ABT162245 . . . WD PACKAGE

		$\overline{}$	
1DIR [1	ر 48	1 <u>0E</u>
1B1 [2	47] 1A1
1B2 [3	46] 1A2
GND [4		GND
1B3	5	44	1A3
1B4		43	1A4
v _{cc} [42	V _{CC}
1B5			1A5
1B6 L			1A6
GND [GND
1B7			1A7
1B8			1A8
2B1			2A1
2B2			2A2
GND [GND
2B3	16		2A3
2B4	17	32	2A4
V _{CC}		31	V _{CC}
2B5			2A5
2B6			2A6
GND [28	GND
2B7			2A7
2B8	1		2 <u>A8</u>
2DIR	24	25	20E

ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SSOP – DL	Tube	SN74ABT162245DL	ADT400045
-40°C to 85°C	550P - DL	Tape and reel	SN74ABT162245DLR	ABT162245
	TSSOP - DGG	Tape and reel	SN74ABT162245DGGR	ABT162245
-55°C to 125°C	CFP – WD	Tube	SNJ54ABT162245WD	SNJ54ABT162245WD

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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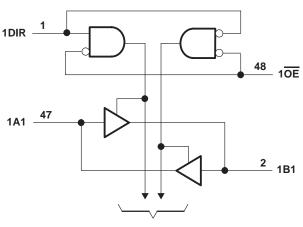
description/ordering information (continued)

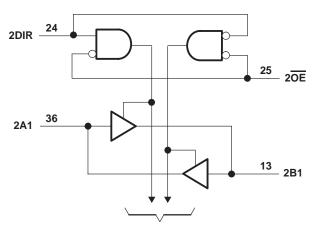
To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE (each 8-bit section)

INP	UTS	
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

logic diagram (positive logic)





To Seven Other Channels To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	
Voltage range applied to any output in the high or power-off state, VO	
Current into any output in the low state, IO: SN54ABT162245 (B port)	96 mA
SN74ABT162245 (B port)	
SN54/74ABT162245 (A port)	
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 2): DGG package	
DL package	
Storage temperature range, T _{stg}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



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recommended operating conditions (see Note 3)

	S			162245	SN74ABT	LINUT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V	
VIH	High-level input voltage		2		2		V
VIL	Low-level input voltage			0.8		0.8	V
٧ _I	Input voltage	0	Vcc	0	Vcc	V	
	I Park Town Landowski summer	B port		-24		-32	4
ЮН	High-level output current	A port		-3		-12	mA
	Lave lavel authors avenues	B port		48		64	A
lOL	Low-level output current	A port		12		12	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN54ABT162245, SN74ABT162245 **16-BIT BUS TRANSCEIVERS** WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED		TEGT COMPLETIONS		Т	T _A = 25°C			SN54ABT162245		SN74ABT162245		
PAR	AMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		$V_{CC} = 4.5 \text{ V},$	$I_{I} = -18 \text{ mA}$			-1.2		-1.2		-1.2	V	
		V _{CC} = 5 V,	$I_{OH} = -1 \text{ mA}$	3.8			2.5		2.5			
	A		$I_{OH} = -1 \text{ mA}$	3.3			3		3			
	A port	V _{CC} = 4.5 V	$I_{OH} = -3 \text{ mA}$	3.1			3		3.1			
V			$I_{OH} = -12 \text{ mA}$	2.6*					2.6		V	
VOH		$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3		3		V	
	D nort		$I_{OH} = -3 \text{ mA}$	2.5			2.5		2.5			
	B port	V _{CC} = 4.5 V	$I_{OH} = -24 \text{ mA}$				2					
			$I_{OH} = -32 \text{ mA}$	2*					2			
	A port		I _{OL} = 12 mA			8.0		0.8		8.0		
VOL	B port	V _{CC} = 4.5 V	$I_{OL} = 48 \text{ mA}$			0.45		0.45		0.45	V	
	Броп		I _{OL} = 64 mA			0.55*				0.55		
V _{hys}	-				100						mV	
l _l	Control inputs	V _{CC} = 5.5 V, V _I = V _{CC} or GND				±1		±1		±1	μА	
	A or B ports]				±20		±20		±20		
IOZH [§]		V _{CC} = 5.5 V,	V _O = 2.7 V			10		10		10	μΑ	
I _{OZL} §		$V_{CC} = 5.5 \text{ V},$	$V_0 = 0.5 V$			-10		-10		-10	μΑ	
l _{off}		$V_{CC} = 0$,	V_I or $V_O \le 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
. ¶	A port	V 55V	V 05V	-25	-50	-100‡	-25	-90	-25	-100	A	
IO¶	B port	$V_{CC} = 5.5 \text{ V},$	$V_0 = 2.5 \text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA	
		V _{CC} = 5.5 V,	Outputs high			2		2		2		
ICC	A or B ports	$I_{O} = 0$,	Outputs low			32		32		32	mA	
		$V_I = V_{CC}$ or GND	Outputs disabled			2		2		2		
	Data inputs ΔI _{CC} #	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1		2		2		
ΔI _{CC} #		Other inputs at VCC or GND Outputs disa				0.05		1		0.05	mA	
	Control inputs	V _{CC} = 5.5 V, One input at 3.4 V, Other inputs at V _{CC} or GND				1.5		1.5		1.5		
Ci		V _I = 2.5 V or 0.5 V			3						pF	
Cio		$V_0 = 2.5 \text{ V or } 0.5 \text{ V}$			6						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



 $^{^\}dagger$ All typical values are at VCC = 5 V. ‡ This limit applies only to the SN74ABT162245.

[§] The parameters I_{OZH} and I_{OZL} include the input leakage current.

Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

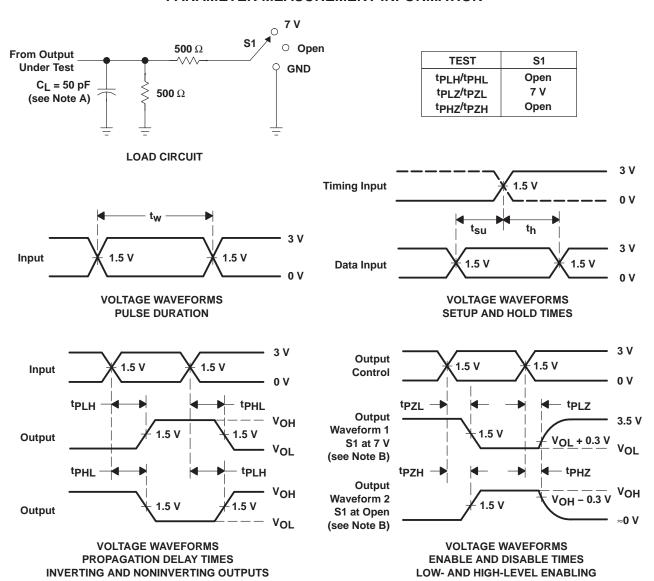
[#] This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V ₍	CC = 5 V A = 25°C	<u>',</u> ;	SN54ABT	162245	SN74ABT	162245	UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH		Б	1	2.2	3.4	1	4.1	1	3.9	
^t PHL	А	В	1	2.3	3.7	1	4.4	1	4.2	ns
^t PLH		•	1	2.7	4.1	1	4.9	1	4.6	
^t PHL	В	Α	1.5	3.1	4.6	1.5	5.2	1.5	5.1	ns
^t PZH	ŌĒ		1	3.6	5.2	1	6.4	1	6.3	
t _{PZL}	OE	В	1	3.7	5.4	1	6.5	1	6.4	ns
^t PHZ	ŌĒ	В	2	4.4	5.8	2	6.4	2	6.3	20
t _{PLZ}	OE .	Ь	1.5	3.3	4.7	1.5	5.6	1.5	5.2	ns
^t PZH			1.5	4.1	6	1.5	7.2	1.5	7.1	
t _{PZL}	ŌĒ	Α	1.5	4.3	6.1	1.5	7.3	1.5	7	ns
^t PHZ	<u> </u>	Δ.	2	4.5	6.1	2	6.8	2	6.6	
tPLZ	OE A	A	1.5	3.7	5.1	1.5	6.1	1.5	5.7	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \,\Omega$, $t_f \leq 2.5 \,$ ns, $t_f \leq 2.5 \,$ ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







i.com 26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9677401QXA	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC
74ABT162245DGGRE4	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ABT162245DLRG4	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT162245DGGR	ACTIVE	TSSOP	DGG	48	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT162245DL	ACTIVE	SSOP	DL	48	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT162245DLR	ACTIVE	SSOP	DL	48	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ABT162245WD	ACTIVE	CFP	WD	48	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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WD (R-GDFP-F**)

CERAMIC DUAL FLATPACK

48 LEADS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only
- E. Falls within MIL STD 1835: GDFP1-F48 and JEDEC MO-146AA

GDFP1-F56 and JEDEC MO-146AB

DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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